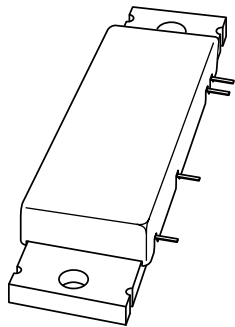


# DATA SHEET



## **BGY1816S** UHF amplifier module

Product specification  
Supersedes data of 1999 Apr 13

2000 Oct 17

# UHF amplifier module

# BGY1816S

### FEATURES

- 26 V nominal supply voltage
- 16 W output power into a load of 50 Ω with an RF drive power of ≤20 mW.

### APPLICATIONS

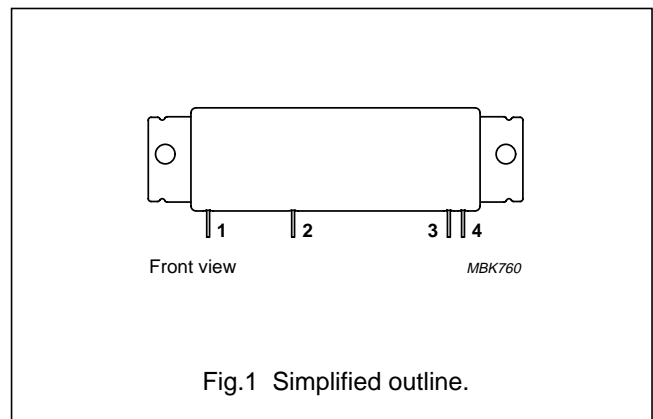
- Base station transmitting equipment operating in the 1805 to 1880 MHz frequency band.

### DESCRIPTION

The BGY1816S is a three-stage UHF amplifier module in a SOT501A package with a plastic cap. It consists of three NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic AlN substrate.

### PINNING - SOT501A

PIN	DESCRIPTION
1	RF input
2	V <sub>S1</sub>
3	V <sub>S2</sub>
4	RF output
Flange	ground



### QUICK REFERENCE DATA

RF performance at T<sub>mb</sub> = 25 °C.

MODE OF OPERATION	f (MHz)	V <sub>S1</sub> (V)	V <sub>S2</sub> (V)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η (%)	Z <sub>S</sub> ; Z <sub>L</sub> (Ω)
CW	1805 to 1880	5	26	≥16	≥29	≥30	50

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>S1</sub>	DC supply voltage		4.5	5.5	V
V <sub>S2</sub>	DC supply voltage		–	28	V
P <sub>D</sub>	input drive power		–	120	mW
P <sub>L</sub>	load power	T <sub>mb</sub> = 25 °C	–	20	W
T <sub>stg</sub>	storage temperature		–30	+100	°C
T <sub>mb</sub>	operating mounting base temperature		–10	+90	°C

## UHF amplifier module

## BGY1816S

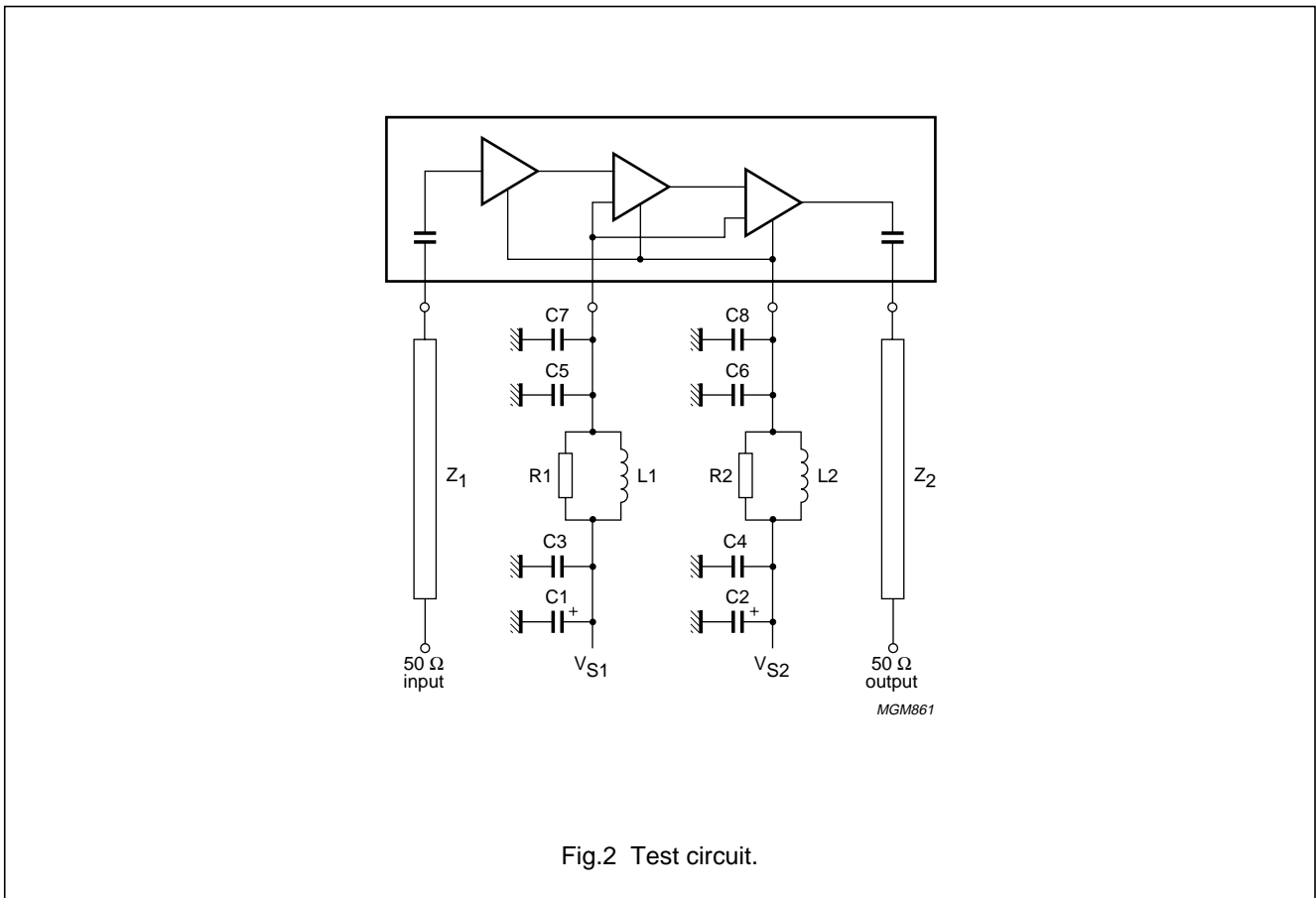
**CHARACTERISTICS**

$T_{mb} = 25\text{ }^{\circ}\text{C}$ ;  $V_{S1} = 5\text{ V}$ ;  $V_{S2} = 26\text{ V}$ ;  $P_L = 16\text{ W}$ ;  $Z_S = Z_L = 50\text{ }\Omega$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f	frequency		1805	–	1880	MHz
$I_{S1}$	supply current		–	80	–	mA
$I_{S2}$	supply current	$P_D < -60\text{ dBm}$	–	430	–	mA
$P_L$	load power	$P_D < 20\text{ mW}$	16	–	–	W
$G_p$	power gain		29	–	–	dB
$\eta$	efficiency		30	–	–	%
$H_2$	second harmonic		–	–	-35	dBc
$H_3$	third harmonic		–	–	-40	dBc
$VSWR_{in}$	input VSWR		–	–	2 : 1	
	stability	$VSWR \leq 2 : 1$ through all phases; $P_L \leq 16\text{ W}$ ; $V_{S2} = 25\text{ to }27\text{ V}$	–	–	-60	dBc
	reverse intermodulation	$P_{carrier} = 16\text{ W}$ ; $P_{reverse} = -40\text{ dBc}$ ; $f_i = f_c \pm 200\text{ kHz}$	–	–	-53	dBc
B	AM bandwidth	corner frequency = 3 dB; $P_{carrier} = 16\text{ W}$ ; modulation = 20%	2	–	–	MHz
	ruggedness	$VSWR \leq 5 : 1$ through all phases	no degradation			

UHF amplifier module

BGY1816S



List of components (see Figs 2 and 3)

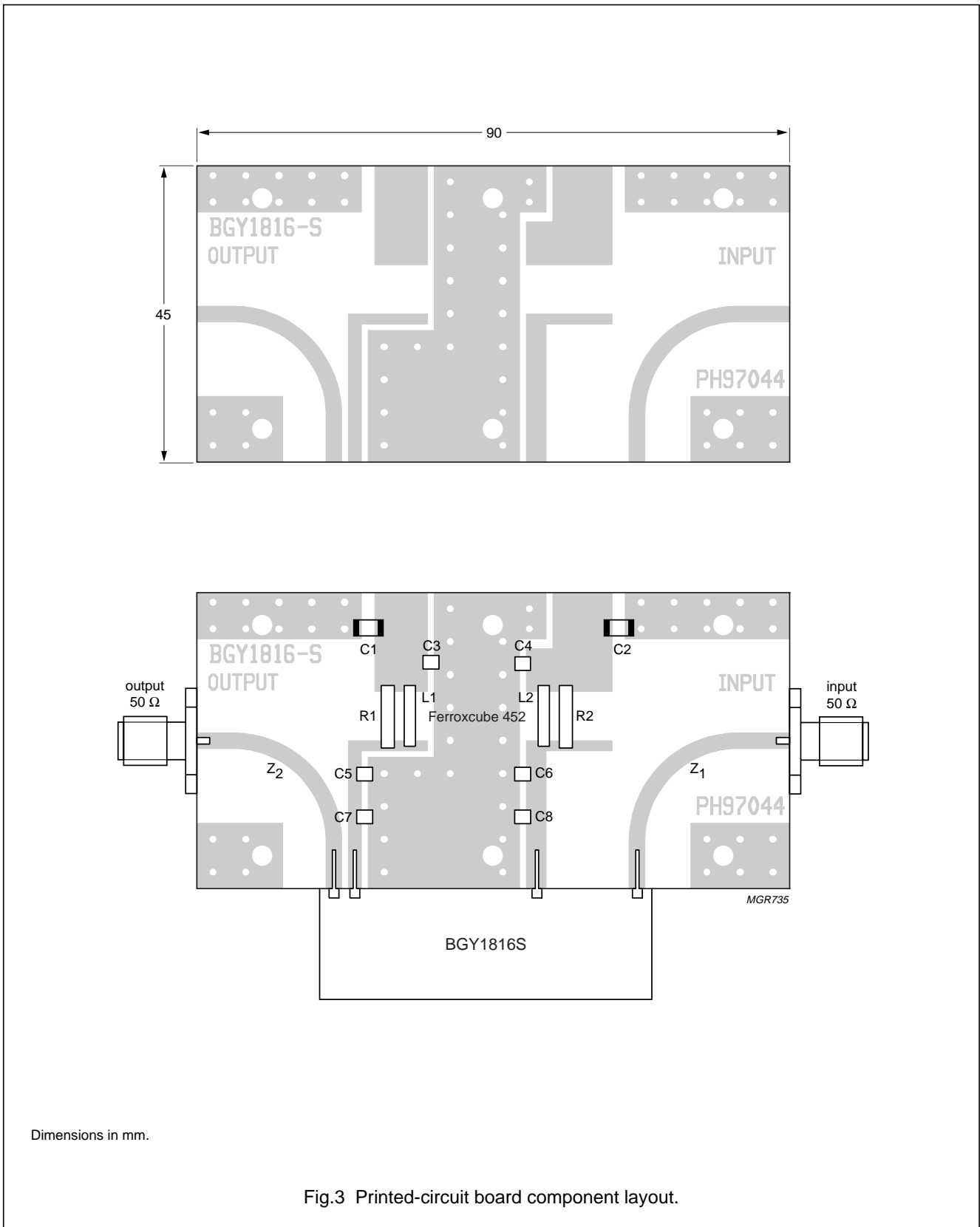
COMPONENT	DESCRIPTION	VALUE	CATALOGUE NO.
C1, C2	electrolytic capacitor	10 μF; 35 V	
C3, C4	multilayer ceramic chip capacitor	10 nF; 50 V	
C5, C6	multilayer ceramic chip capacitor	100 pF; 50 V	
C7, C8	multilayer ceramic chip capacitor	10 pF; 50 V	
L1, L2	Grade 4S2 Ferroxcube bead		4330 030 36300
R1, R2	metal film resistor	10 Ω; 0.4 W	2322 195 13109
Z1, Z2	stripline; note 1	50 Ω	–

Note

1. The striplines are on a double copper-clad printed-circuit board (RO5880) with  $\epsilon_r = 2.2$  and thickness = 0.79 mm.

UHF amplifier module

BGY1816S



Dimensions in mm.

Fig.3 Printed-circuit board component layout.

---

## UHF amplifier module

## BGY1816S

---

### **MOUNTING RECOMMENDATIONS**

To ensure a good thermal contact and to prevent mechanical stress when bolted down, the flatness of the mounting base is designed to be typically better than 0.1 mm. The mounting area of the heatsink should be flat and free from burrs and loose particles. The heatsink should be rigid and not prone to bowing under thermal cycling conditions. The thickness of a solid heatsink should be not less than 5 mm to ensure a rigid assembly.

A thin, even layer of thermal compound should be applied between the mounting base and the heatsink to achieve the best possible thermal contact resistance. Excessive use of thermal compound will result in an increase in thermal resistance and possible bowing of the mounting base; too little will also result in poor thermal conduction.

The module should be mounted to the heatsink using 3 mm bolts with flat washers. The bolts should first be tightened to "finger tight" and then further tightened in alternating steps to a maximum torque of 0.4 to 0.6 Nm.

Once mounted on the heatsink, the module leads can be soldered to the printed-circuit board. A soldering iron may be used up to a temperature of 250 °C for a maximum of 10 seconds at a distance of 2 mm from the plastic cap.

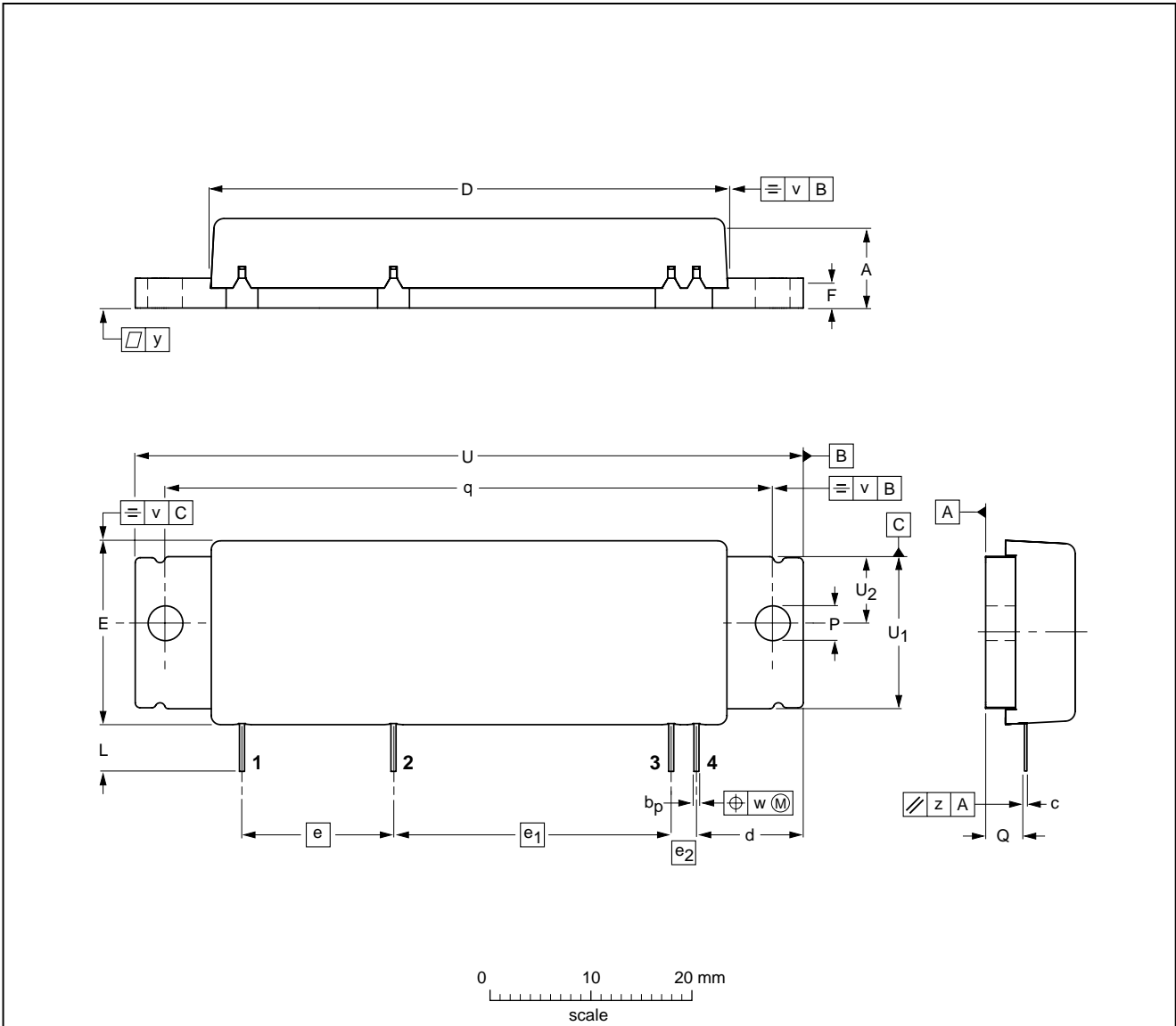
ESD precautions must be taken to protect the device from electrostatic damage.

UHF amplifier module

BGY1816S

PACKAGE OUTLINE

Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 4 in-line leads SOT501A



DIMENSIONS (mm are the original dimensions)

UNIT	A	b <sub>p</sub>	c	D	d	E	e	e <sub>1</sub>	e <sub>2</sub>	F	L	P	Q	q	U	U <sub>1</sub>	U <sub>2</sub>	v	w	y	z
mm	9.4 8.9	0.56 0.46	0.3 0.2	52.1 51.7	10.9 10.5	18.7 18.3	15.24	27.94	2.54	3.1 2.9	6.5 6.1	3.6 3.4	4.1 3.7	61.2 61.0	67.4 67.0	15.5 15.1	6.9 6.5	0.2	0.25	0.1	0.3

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT501A					98-10-28

## UHF amplifier module

BGY1816S

## DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS <sup>(1)</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

## Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

## DEFINITIONS

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

## DISCLAIMERS

**Life support applications** — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

**Right to make changes** — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.



UHF amplifier module

BGY1816S

---

**NOTES**

UHF amplifier module

BGY1816S

---

**NOTES**

UHF amplifier module

BGY1816S

---

**NOTES**

# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 3 Figtree Drive, HOMEBUSH, NSW 2140,  
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

**Austria:** Computerstr. 6, A-1101 WIEN, P.O. Box 213,  
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

**Belgium:** see The Netherlands

**Brazil:** see South America

**Bulgaria:** Philips Bulgaria Ltd., Energoproject, 15th floor,  
51 James Bourchier Blvd., 1407 SOFIA,  
Tel. +359 2 68 9211, Fax. +359 2 68 9102

**Canada:** PHILIPS SEMICONDUCTORS/COMPONENTS,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**China/Hong Kong:** 501 Hong Kong Industrial Technology Centre,  
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,  
Tel. +852 2319 7888, Fax. +852 2319 7700

**Colombia:** see South America

**Czech Republic:** see Austria

**Denmark:** Sydhavnsgade 23, 1780 COPENHAGEN V,  
Tel. +45 33 29 3333, Fax. +45 33 29 3905

**Finland:** Sinikalliontie 3, FIN-02630 ESPOO,  
Tel. +358 9 615 800, Fax. +358 9 6158 0920

**France:** 51 Rue Carnot, BP317, 92156 SURESNES Cedex,  
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

**Germany:** Hammerbrookstraße 69, D-20097 HAMBURG,  
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Band Box Building, 2nd floor,  
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,  
Tel. +91 22 493 8541, Fax. +91 22 493 0966

**Indonesia:** PT Philips Development Corporation, Semiconductors Division,  
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,  
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

**Ireland:** Newstead, Clonskeagh, DUBLIN 14,  
Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,  
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),  
Tel. +39 039 203 6838, Fax +39 039 203 6800

**Japan:** Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,  
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
Tel. +82 2 709 1412, Fax. +82 2 709 1415

**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
Tel. +60 3 750 5214, Fax. +60 3 757 4880

**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
Tel. +31 40 27 82785, Fax. +31 40 27 88399

**New Zealand:** 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,  
Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
Tel. +47 22 74 8000, Fax. +47 22 74 8341

**Pakistan:** see Singapore

**Philippines:** Philips Semiconductors Philippines Inc.,  
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,  
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

**Poland:** Al.Jerozolimskie 195 B, 02-222 WARSAW,  
Tel. +48 22 5710 000, Fax. +48 22 5710 001

**Portugal:** see Spain

**Romania:** see Italy

**Russia:** Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,  
Tel. +7 095 755 6918, Fax. +7 095 755 6919

**Singapore:** Lorong 1, Toa Payoh, SINGAPORE 319762,  
Tel. +65 350 2538, Fax. +65 251 6500

**Slovakia:** see Austria

**Slovenia:** see Italy

**South Africa:** S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,  
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,  
Tel. +27 11 471 5401, Fax. +27 11 471 5398

**South America:** Al. Vicente Pinzon, 173, 6th floor,  
04547-130 SÃO PAULO, SP, Brazil,  
Tel. +55 11 821 2333, Fax. +55 11 821 2382

**Spain:** Balmes 22, 08007 BARCELONA,  
Tel. +34 93 301 6312, Fax. +34 93 301 4107

**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

**Switzerland:** Allmendstrasse 140, CH-8027 ZÜRICH,  
Tel. +41 1 488 2741 Fax. +41 1 488 3263

**Taiwan:** Philips Semiconductors, 5F, No. 96, Chien Kuo N. Rd., Sec. 1,  
TAIPEI, Taiwan Tel. +886 2 2134 2451, Fax. +886 2 2134 2874

**Thailand:** PHILIPS ELECTRONICS (THAILAND) Ltd.,  
60/14 MOO 11, Bangna Trad Road KM. 3, Bagna, BANGKOK 10260,  
Tel. +66 2 361 7910, Fax. +66 2 398 3447

**Turkey:** Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,  
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**Uruguay:** see South America

**Vietnam:** see Singapore

**Yugoslavia:** PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,  
Tel. +381 11 3341 299, Fax.+381 11 3342 553

**For all other countries apply to:** Philips Semiconductors,  
Marketing Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN,  
The Netherlands, Fax. +31 40 27 24825

**Internet:** <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 2000

SCA 70

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

613524/04/pp12

Date of release: 2000 Oct 17

Document order number: 9397 750 07588

*Let's make things better.*

**Philips  
Semiconductors**



**PHILIPS**